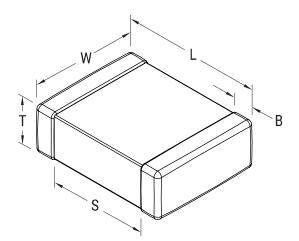


C0805C332K2RAC7210

SMD Comm X7R, Ceramic, 3,300 pF, 10%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X7R	
Style	SMD Chip	
Description	SMD, MLCC, Temperature Stable, Class II	
Features	Temperature Stable, Class II	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	11 mg	
Shelf Life	78 Weeks	
MSL	1	

	Specifications	
3,300 pF	Capacitance	0805
1 kHz 1.0Vrms	Measurement Condition	2mm +/-0.2mm
10%	Tolerance	1.25mm +/-0.2mm
200 VDC	Voltage DC	0.78mm +/-0.10mm
oltage 500 VDC	Dielectric Withstanding Volta	0.7mm MIN
-55/+125°C	Temperature Range	0.5mm +/-0.25mm
X7R	Temp. Coefficient	
Capacitance Change with 15%, 1kHz 1.0		
Reference to +25°Č and 0 VDC Applied (TCC)		T&R, 330mm, Paper Tape
2.5% 1 kHz 1.0V	Dissipation Factor	15000
200 VDC 500 VDC -55/+125°C X7R VDC	Voltage DC Dielectric Withstanding Volta Temperature Range Temp. Coefficient Capacitance Change with Reference to +25°C and 0 VE Applied (TCC)	0.78mm +/-0.10mm 0.7mm MIN 0.5mm +/-0.25mm T&R, 330mm, Paper Tape

Aging Rate

Insulation Resistance

 Dimensions

 Chip Size
 0805

 L
 2mm +/-0.2mm

 W
 1.25mm +/-0.2mm

 T
 0.78mm +/-0.10mm

 S
 0.7mm MIN

 B
 0.5mm +/-0.25mm

Packaging SpecificationsPackagingT&R, 330mm, Paper TaPackaging Quantity15000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

3% Loss/Decade Hour: Referee Time is 1000 Hours

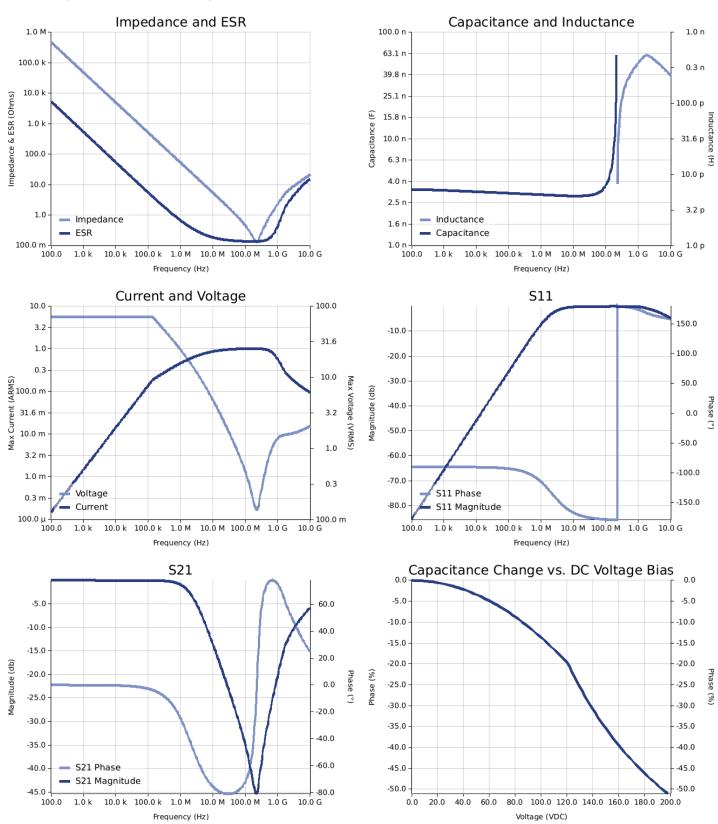
100 GOhms



CO805C332K2RAC7210 SMD Comm X7R, Ceramic, 3,300 pF, 10%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm

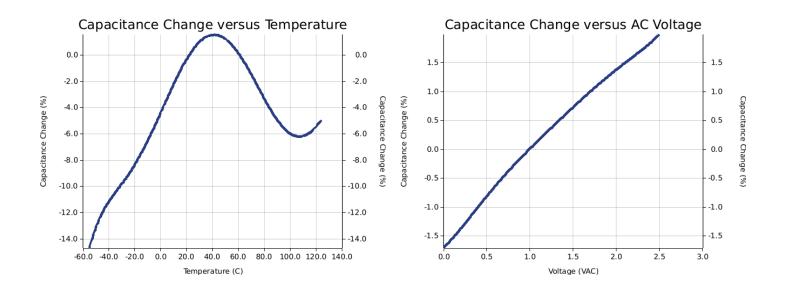
Simulations

For the complete simulation environment please visit K-SIM.





CO805C332K2RAC7210 SMD Comm X7R, Ceramic, 3,300 pF, 10%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm





SMD Comm X7R, Ceramic, 3,300 pF, 10%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics.
 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.